a)
$$U(x) = C_2 x^2 - C_3 x^3 - C_4 x^4$$

Assignment #5 Solutions: Independently by

- 1) Kevin Lee
- 2) Zach Zeigler

Assume the system satisfies Boltzmann Statistics

Hence, the expectation value of
$$x$$
 is following.

 $\langle x \rangle = \int_{-\infty}^{\infty} x \cdot e^{-\frac{\chi(x)}{k_B T}} dx$

$$\langle \chi \rangle = \frac{\int_{-\infty}^{\infty} \chi \cdot e^{-\frac{k_B T}{k_B T}} d\chi}{\int_{-\infty}^{\infty} e^{-\frac{k_B T}{k_B T}} d\chi}$$

$$= \frac{\int_{-\infty}^{\infty} \chi \cdot e^{-\frac{k_B T}{k_B T}} d\chi}{\int_{-\infty}^{\infty} e^{-\frac{k_B T}{k_B T}} d\chi}$$

$$= \frac{\int_{-\infty}^{\infty} \chi \cdot e^{-\frac{k_B T}{k_B T}} d\chi}{\int_{-\infty}^{\infty} e^{-\frac{k_B T}{k_B T}} d\chi}$$

, Let
$$\beta = \frac{1}{k_BT}$$

Let's assume x is small. Cz is the dominant term.

Therefore, C3 and C4 have relatively small contributions.

We take the Taylor expansion of C3 and C4 terms.

$$\langle \chi \rangle = \frac{\int_{-\infty}^{\infty} \chi(1+\beta C_3 \chi^3 + \beta C_4 \chi^4 + ...) e^{-\beta C_2 \chi^2} d\chi}{\int_{-\infty}^{\infty} (1+\beta C_3 \chi^3 + \beta C_4 \chi^4 + ...) e^{-\beta C_2 \chi^2} d\chi}$$

$$\approx \frac{\int_{-\infty}^{\infty} (x + \beta c_3 x^4 + \beta c_4 x^5) e^{-\beta c_2 x^2}}{\sqrt{2}}$$

$$\int_{-\infty}^{\infty} \left(1 + \beta C_3 \times^3 + \beta C_4 \times^4 \right) e^{-\beta C_2 \chi^2} dx$$

Note:
$$\int_{-\infty}^{\infty} x e^{-\beta C_1 x^2} dx = \int_{-\infty}^{\infty} \beta C_4 x^5 e^{-\beta C_2 x^2} dx = 0$$

$$\int_{-\infty}^{\infty} \beta C_3 x^3 e^{-\beta C_2 x^2} dx = 0$$

a) Continued.
$$\langle \chi \rangle \approx \frac{\int_{-\infty}^{\infty} \beta C_3 x^4 e^{-\beta C_2 x^2} dx}{\int_{-\infty}^{\infty} (1+\beta C_4 x^4) e^{-\beta C_2 x^2} dx}$$

Now we only need to evaluate the two integrals.

$$\int_{-\infty}^{\infty} \beta C_3 x^4 e^{-\beta C_1 x^2} dx, \qquad \text{Let} \qquad x^2 = \frac{y}{\beta C_2}, \qquad x = \frac{\sqrt{y}}{\sqrt{\beta C_2}}$$

Let
$$x^2 = \frac{y}{\beta c_2}$$
, $x = \frac{\sqrt{y}}{\sqrt{\beta c_2}}$.
$$dx = \frac{1}{\sqrt{\beta c_2}} \cdot \frac{dy}{\sqrt{y}}$$

$$=2\int_{0}^{\infty}\beta C_{3}x^{4}e^{-\beta C_{2}x^{2}}dx$$

$$= 2 \cdot \int_{0}^{\infty} \beta C_{3} \cdot \frac{y^{2}}{\beta^{2}C_{2}} = \frac{y}{\sqrt{\beta C_{2}}} \cdot \frac{dy}{\sqrt{y}}$$

$$= 2 \beta C_3 \cdot \frac{1}{(\beta C_2)^{\frac{5}{2}}} \int_0^{\infty} y^{\frac{3}{2}} e^{-y} dy$$

$$= 2\beta C_3 \cdot \frac{1}{(\beta C_2)^{\frac{1}{2}}} \Gamma(\frac{5}{2}) = 2\beta C_3 \cdot \frac{1}{(\beta C_2)^{\frac{3}{2}}} \cdot \frac{3}{4} \sqrt{11}$$

$$\int_{-\infty}^{\infty} (1+\beta C_4 X^4) e^{-\beta C_2 X^2} dx = 2 \int_{0}^{\infty} e^{-\beta C_2 X^2} dx + 2 \int_{0}^{\infty} \beta C_4 X e^{-\beta C_2 X^2} dx$$

$$= 2 \int_{0}^{\infty} \frac{y^{-\frac{1}{2}}}{\sqrt{\beta c_{2}}} e^{-y} dy + 2 \beta c_{4} \cdot \frac{1}{(\beta c_{2})^{\frac{5}{2}}} \frac{3}{4} \sqrt{\pi}$$

$$= \frac{2}{J\beta C_2} J\pi + \lambda \beta C_4 \frac{1}{(\beta C_2)^2} \stackrel{3}{=} \sqrt{\pi}$$

Similar to previous

a) Continued.

$$\langle \chi \rangle = \frac{\beta C_3 (\beta C_2)^{-\frac{5}{2}} \cdot \frac{3}{4} \sqrt{\chi}}{\sqrt{\beta C_2}} + \chi \beta C_4 \cdot (\beta C_2)^{-\frac{5}{2}} \frac{3}{4} \sqrt{\chi} \qquad (\beta C_2)^{\frac{3}{2}} + \beta C_4 \cdot \frac{3}{4}$$

$$= \frac{3 C_{3} \beta}{4 \beta^{2} C_{2}^{2} + 3 \beta C_{4}} = \frac{3(\frac{C_{3}}{\beta})}{4 C_{2}^{2} + 3(\frac{C_{4}}{\beta})}, \beta = \frac{1}{4 C_{1}^{2}}$$

Neglect the forth power term.

$$\langle x \rangle \approx \frac{3 C_3 k_B T}{4 C_2^2}$$

Coefficient of thermal expansion =
$$\frac{\partial(x)}{\partial T}$$

$$= \frac{3 C_3 k_B}{4 C_2^2}$$

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b)
$$\vec{J}_{heat} = \sum_{g} N_{g} \cdot \hbar \omega_{g} \cdot \vec{v}_{g} = -\kappa_{L} \cdot \nabla T$$

$$\frac{N_{q}-N_{q}^{2}}{T_{q}}=-\left(\overrightarrow{\eta}\cdot\nabla T\right)\frac{\partial N_{q}^{2}}{\partial T}$$

$$\vec{v}_g = \frac{1}{\hbar} \frac{\partial \hbar \omega}{\partial q}$$

$$= \sum_{1}^{2} N_{7}^{\circ} t_{w_{7}} \cdot \vec{v}_{7} = 0$$

$$K_{L} = \sum_{g} |\vec{v}_{g}|^{2} \hbar \omega_{g} \cdot \frac{\hbar \omega_{g}}{k_{B}T} \cdot \frac{\hbar \omega_{g}}$$

$$D(w) dw = \frac{4\pi q^2 dq}{\left(\frac{2\pi}{L}\right)^3} = \frac{4\pi q^2 dq}{(2\pi)^3} V = \frac{4\pi q^2 dqV}{8\pi^{82}} = \frac{q^2 dqV}{2\pi^2}$$

$$D(\omega) = \frac{Vq^2}{2\pi^2} \left(\frac{d\omega}{dq}\right)^{-1} = \frac{Vq^2}{2\pi^2} \cdot \frac{1}{V_s} = \frac{V\omega^2}{2\pi^2 v_s^3}$$

$$\sum_{q} \rightarrow \int_{0}^{q} d^{3}q = \int_{0}^{\infty} D(\omega) d\omega$$

$$K_{L} = \int_{0}^{W_{D}} \frac{V_{W_{0}}^{2}}{2\pi^{2}v_{s}^{2}} T_{0}^{2} v_{s}^{2} \cdot h_{W_{0}}(\frac{1}{V}) \frac{h_{W_{0}}^{2}}{k_{B}T} \left(e^{\frac{h_{W_{0}}^{2}}{k_{B}T}} - 1\right)^{2} dw_{0}^{2}$$

$$= \frac{1}{2\pi^{2}v_{s}} \int_{0}^{W_{D}} \left(h_{W_{0}^{2}}\right)^{2} \frac{w_{0}^{2}}{k_{B}T} \frac{h_{W_{0}^{2}}^{2}}{k_{B}T} dw_{0}^{2}$$

$$= \frac{1}{2\pi^{2}v_{s}} \int_{0}^{W_{D}} \left(h_{W_{0}^{2}}\right)^{2} \frac{w_{0}^{2}}{k_{B}T} \frac{h_{W_{0}^{2}}^{2}}{k_{B}T} dw_{0}^{2}$$

$$= \frac{1}{2\pi^{2}v_{s}} \int_{0}^{W_{D}} \left(h_{W_{0}^{2}}\right)^{2} \frac{w_{0}^{2}}{k_{B}T} \frac{h_{W_{0}^{2}}^{2}}{k_{B}T} dw_{0}^{2}$$

$$= \frac{1}{2\pi^{2}v_{s}} \int_{0}^{W_{0}^{2}} \left(h_{W_{0}^{2}}\right)^{2} \frac{h_{W_{0}^{2}}^{2}}{k_{B}T} \frac{h_{W_{0}^{2}}^{2}}{k_{B}T} dw_{0}^{2}$$

$$= \frac{1}{2\pi^{2}v_{s}} \int_{0}^{W_{0}^{2}} \left(h_{W_{0}^{2}}\right)^{2} \frac{h_{W_{0}^{2}}^{2}}{k_{B}T} \frac{h_{W_{0}^{2}}$$

$$K_{L} = \frac{1}{2\pi^{2}v_{s}} \int_{0}^{x_{D}} \frac{\left(\frac{k_{B}T}{\hbar}\right)^{4} \chi^{4} \cdot e^{x}}{\left(\frac{k_{B}T}{\hbar}\right)^{2} \chi^{4} \cdot \left(\frac{k_{B}T}{\hbar}\right) d\chi} \cdot \left(\frac{k_{B}T}{\hbar}\right) d\chi$$

$$= \frac{t^{2}}{2\pi^{2}v_{s}} \left(\frac{1}{\sqrt{t}}\right) \left(\frac{k_{B}T}{t}\right) \left(\frac{k_{B}T}{t}\right)^{4} \int_{0}^{x_{D}} \frac{x^{4} e^{x}}{\sqrt{t_{g}^{2}\left(e^{x}-1\right)^{2}}} dx$$

$$= \frac{k_B}{2\pi^2 v_s} \left(\frac{k_B T}{t}\right)^3 \int_0^{8p} \frac{x^4 e^x}{z_q! \left(e^x - 1\right)^2} dx$$

c)

$$\kappa_L = A \frac{\overline{M}\theta^3 \delta}{\gamma^2 T n^{\frac{2}{3}}}$$

n: number of atoms per unit cell

 θ : traditional Debye temperature(determined by elastic constants or specific heat)

 \overline{M} : average atomic mass

y: Gruneisen parameter

A: a constant has γ – dependence

Assume it's under room temperature condition T=300K.

• For silicon (Si), n=2, $\theta_a=395K=\theta n^{-1/3}$, $\gamma=1.06$, $\overline{M}=28.08$ amu, $\delta=2.71 \text{Å}$.

The calculated thermal conductivity for Si is $\kappa_{Si} = 0.59Wcm^{-1}K^{-1}$.

• For GaAs, n=2, $\theta_a=220K=\theta n^{-1/3}$, $\gamma=0.75$, $\overline{M}=72.32$ amu, $\delta=2.83$ Å.

The calculated thermal conductivity for GaAs is $\kappa_{GaAs} = 0.55 W cm^{-1} K^{-1}$.

- For GaN, n=4, $\theta_a=390K=\theta n^{-1/3}$, $\gamma=0.7$, $\overline{M}=41.87$ amu, $\delta=2.25$ Å. The calculated thermal conductivity for GaN is $\kappa_{GaN}=2.01Wcm^{-1}K^{-1}$.
- For AIN, n=4, $\theta_a=620K=\theta n^{-1/3}$, $\gamma=0.7$, $\overline{M}=20.49$ amu, $\delta=3.03$ Å. The calculated thermal conductivity for AIN is $\kappa_{AIN}=5.31Wcm^{-1}K^{-1}$.
- For SiC, n=4, $\theta_a=740K=\theta n^{-1/3}$, $\gamma=0.75$, $\overline{M}=20.0$ amu, $\delta=2.18 \text{Å}$. The calculated thermal conductivity for SiC is $\kappa_{SiC}=5.61Wcm^{-1}K^{-1}$.
- For BN, there is anisotropy in the thermal conductivities. BN-xy, n=4, $\theta_a=1442K=\theta n^{-1/3}$, $\gamma=0.75$, $\overline{M}=12.4$ amu, $\delta=2.05$ Å. The calculated thermal conductivity for BN-xy is $\kappa_{BN-xy}=24.2Wcm^{-1}K^{-1}$. BN-z, n=4, $\theta_a=755K=\theta n^{-1/3}$, $\gamma=2$, $\overline{M}=12.4$ amu, $\delta=2.05$ Å. The calculated thermal conductivity for BN-z is $\kappa_{BN-z}=0.44Wcm^{-1}K^{-1}$.
- For Diamond, $n=2, \theta_a=1450K=\theta n^{-1/3}, \gamma=0.75, \overline{M}=12.01 \ amu, \delta=1.78 \mbox{Å}.$

The calculated thermal conductivity for Diamond is $\kappa_{Diamond} = 16.42Wcm^{-1}K^{-1}$.

d)

Intuitively, when there is an additional scattering process, the overall thermal conductivity should decrease. It can be explained using the Part b's expression for thermal conductivity.

$$\kappa_L = \frac{k_B}{2\pi^2 v_s} \left(\frac{k_B T}{\hbar}\right)^3 \int_0^{\theta_D/T} dx \frac{x^4 e^x}{\tau_q^{-1}(x)(e^x - 1)^2}$$

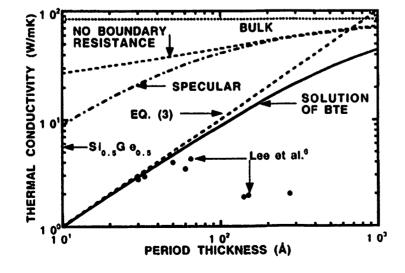
$$\kappa_L \propto \tau_q$$

And the total relaxation time can be evaluated as following.

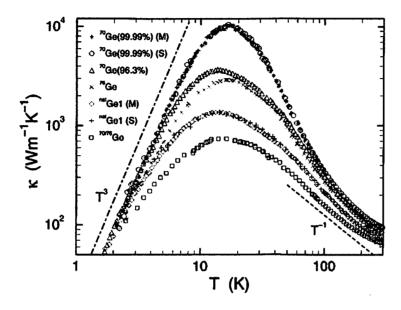
$$\tau_q^{-1} = \sum_i \tau_i^{-1}$$

If there is one more scattering term, the total relaxation time will decrease, then reduces the thermal conductivity.

- For alloys, we can expect that the relaxation time would be reduced due to the alloy scattering process.
- For superlattices, there are several scattering processes in comparison with its binary constituents. When the superlattice's thickness is below critical thickness, the reduction is due to diffuse interface scattering. G. Chen et al used Boltzmann transport equation to solve the thermal conductivity reduction behavior in the Si/Ge superlattices. [1] As show in following figure, the cross plane thermal conductivity is reduced two order compared with bulk part. When the superlattice's thickness exceeds the critical thickness, the dislocation scattering becomes the dominant scattering process.



For isotopes, there is isotopes scattering in the crystal. As we can see from
 Asen-Palmer et al's article [2], the pure ⁷⁰Ge(99.99%) has the highest thermal
 conductivity. As the crystal contains more isotopes, the thermal conductivity
 starts decreasing due to the isotope scattering process.



[1] Chen, G. and Neagu, M., "Thermal conductivity and heat transfer in superlattices", Applied Physics Letters, 71, 2761-2763 (1997), DOI:http://dx.doi.org/10.1063/1.120126

[2] M. Asen-Palmer, K. Bartkowski, E. Gmelin, M. Cardona, A. P. Zhernov, A. V. Inyushkin, A. Taldenkov, V. I. Ozhogin, K. M. Itoh, and E. E. Haller, "Thermal conductivity of germanium crystals with different isotopic compositions", Phys. Rev. B 56, 9431

- a) Rockett Problem 10.14. # 1.
 - (a) Distance between substrate and source = 30 cm

$$0 = 4 \times 10^{-15} \text{ cm}^2$$

Equation [0.]
$$\lambda_{mfp} = \frac{k_{B}T}{\sqrt{2} \sigma P}, T = 300K$$

$$P = \frac{k_B T}{\sqrt{\sum \sigma \cdot \lambda_m f_p}}$$

$$P = \frac{k_B T}{\sqrt{5} \tau \cdot \lambda_{mfp}} = 7.32 \times 10^{-2} P_a = 5.49 \times 10^{-4} Torr$$

$$P = > 44 \times 10^{-1} P_a = 1.83 \times 10^{-3} Torr$$

b) Rockett Problem 10.14#2

$$f = \frac{P}{\sqrt{2\pi m k_B T}}$$

$$F_{Ga} = 5 \times 10^{14} \text{ cm}^{-3} \cdot 5^{-1} = \frac{1 \text{ Ga}}{\sqrt{2\pi \text{ m}_{Ga} \text{kgT}_{Ga}}}$$
 $P_{Ga} = 5 \times 10^{-4} \text{ Pa}$

$$F_{As_4} = 2 \times 10^{16} \text{ cm}^{-d} \cdot \text{s}^{-1} = \frac{P_{As_4}}{\sqrt{277} M_{As_4} k_B T_{As_4}}$$
 $P_{As_4} = 2.94 \times 10^{-2} P_a$

$$P_{Asq} = 2.94 \times 10 \text{ Ta}$$

(b)
$$5 = 4 \times 10^{15} \text{ cm}^2 = 4 \times 10^{-19} \text{ cm}^2$$

 $2 \times 10^{15} \text{ cm}^2 = 4 \times 10^{-19} \text{ cm}^2$
 $2 \times 10^{15} \text{ cm}^2 = 4 \times 10^{-19} \text{ cm}^2$
 $2 \times 10^{15} \text{ cm}^2 = 4 \times 10^{-19} \text{ cm}^2$

(c) No, the Ga atom wouldn't be scattered significantly by Asa vapors. The mean free path for Ga atom in Asy vapor is almost one meter long. A typical MBE or other growth chamber's substrate to source distance is smaller than this value. Therefore, there would be very small chance for Ga atom to be scattered by Asq atom.

a)

Surface.

Assume the gas particle's velocity distribution

Maxwell-Boltzmann Listribution.

 $P(v_{x}, v_{y}, v_{z}) = C \cdot e^{-\frac{1}{2}m(v_{x}^{2} + v_{y}^{2} + v_{z}^{2})}$

normalization constant

$$\int_{-\infty}^{\infty} \int_{-\infty}^{\infty} \int_{-\infty}^{\infty} \int_{-\infty}^{\infty} dv_x dv_y dv_z \quad C \cdot e^{-\frac{1}{2} \frac{m(v_x^2 + v_y^2 + v_z^2)}{\xi_B T}}$$

$$= C \cdot \left(\sqrt{\frac{\pi}{\frac{m}{2k_0 T}}} \right)^3 = C \cdot \frac{\left(2k_3 T \pi\right)^{\frac{3}{2}}}{m^{\frac{3}{2}}}$$

 $C = \left(\frac{m}{2\pi k_{\bullet} T}\right)^{\frac{3}{2}}$

 $C = \left(\frac{1}{2\pi k_B T}\right)$ We've considering only those particles $V = C \cdot \int_{-\infty}^{\infty} dv_x \int_{-\infty}^{\infty} dv_y \int_{0}^{\infty} dv_z \cdot v_z \cdot v_z$

=
$$\left(\frac{m}{2\pi k_B T}\right)^{\frac{3}{2}} \cdot \frac{2\pi k_B T}{m} \cdot n \int_{0}^{\infty} dU_z \cdot V_z \cdot e^{-\frac{m}{2k_B T}} (V_z^2)$$

$$= \frac{\left(\frac{m}{2\pi k_BT}\right)^{\frac{3}{2}} \left(\frac{2\pi k_BT}{m}\right) \cdot n \cdot \frac{1}{2\pi k_BT}}{\left(\frac{m}{2\pi k_BT}\right)^{\frac{3}{2}} \left(\frac{m}{2\pi k_BT}\right)^{\frac{3}{2}} \cdot \frac{2\pi n k_BT}{m^2} \cdot k_BT}$$

$$= \left(\frac{1}{2\pi k_BT}\right)^{\frac{3}{2}} \cdot \frac{2\pi \cdot P}{m^2} \cdot k_BT} = \frac{P}{2\pi m k_BT}$$

$$= \frac{1}{2\pi m k_BT} \cdot \frac{1}{m^2} \cdot \frac{1}$$

$$= \left(\frac{1}{2\pi k_{B}T}\right)^{\frac{3}{2}} \cdot \frac{2\pi \cdot P}{m^{\frac{1}{2}}} \cdot k_{B}T = \frac{P}{2\pi m_{B} k_{B}T}$$

$$f = \frac{P}{\sqrt{\frac{10^{-10} \text{ Torr}}{133 \times 10^{-8} \text{ Pa}}}} = \frac{1.33 \times 10^{-8} \text{ Pa}}{\sqrt{\frac{1.33 \times 10^{-8}}{1.33 \times 10^{-8}}}}$$

$$M = 14 \times d$$
 amu = $28 \times 1.66 \times 10^{-27} \text{ kg}$
 $f = 3.8 \times 10^{-14} \text{ molecules / m}^2 \cdot \text{s}$
 $= 3.82 \times 10^{-14} \text{ molecules / (100)}^2 \text{ cm}^2 \cdot \text{s}$
 $= 3.82 \times 10^{-14} \text{ molecules / (100)}^2 \text{ cm}^2 \cdot \text{s}$

No, I don't think there would be growth on the GaN surface.

No molecules can be adsorbed on the GaN surface.

But the bonding between nitrogen atoms are very strong, and can't be broken easily. Generally, it would require a plasma Source to break the bonding of No molecules.

0)

$$N_1 = \frac{P_1 V_1}{k_B T}$$

$$P_{2}V = (N_{1}+N_{2})k_{B}T = \left(\frac{P_{1}V}{k_{B}T}+N_{2}\right)k_{B}T$$

$$= P_{1}V + N_{2}k_{B}T$$

$$= P_{1}V + N_{2}k_{B}T$$

$$N_2 k_BT = (P_2 - P_1)V$$

$$f_0 = \frac{P_2 - P_1}{\sqrt{2\pi m k_B T}} = \frac{(10^{-9} - 10^{-10}) \times 133}{\sqrt{2\pi m_0 k_B T}} = 4.55 \times 10^{15} \text{ atoms/}$$

$$m^2.5$$

 $M_0 = 16 \text{ amu}$

$$f_0 = 4.55 \times 10^{11} \text{ atoms}$$

Sticking Coefficient

=
$$4.55 \times 10^{11} \times 0.05 = 2.28 \times 10^{10}$$
 atoms/

Leak was instaneous. And GaN exposed to Oxygen for 10 min.

d)

The contamination oxygen incorporated into the surface will cause additional doping to GaN. Therefore, it induces band bending at the interface. This band bending then becomes the barrier for hole transport.

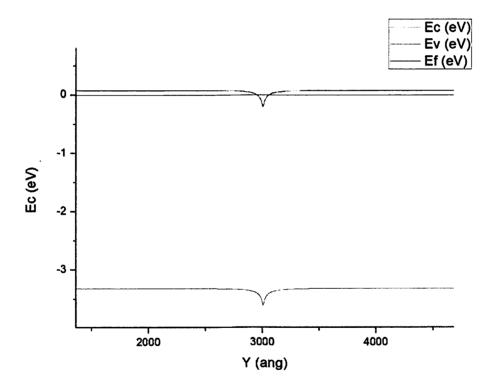
This is the simulation result from 1D Poisson. I assume the interface thickness is 1nm. The total sheet impurity concentration should be the same, which means

$$\sigma_0 = 1.37 \times 10^{13} cm^{-2}$$

Effective donor concentration is

$$N_D = \frac{\sigma_0}{1 \times 10^{-7} cm} = 1.37 \times 10^{20} cm^{-3}$$

We can estimate the barrier height for hole transport using 1D Poisson.



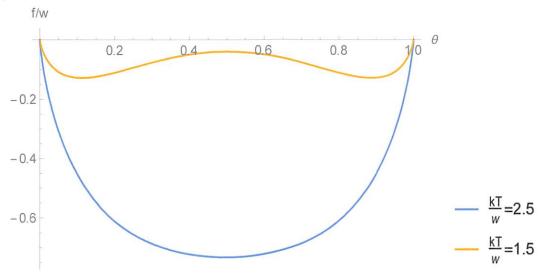
The barrier height is estimated to be 0.286eV.

a)

From Taso's Chapter 6, we can write down the free energy per site as following.

$$\frac{f_{adat}}{\omega} = 4\theta(1-\theta) + \frac{kT}{\omega} [\theta ln\theta + (1-\theta)ln(1-\theta)]$$

With the above equation, we can draw the plot for two normalized temperatures. The orange curve represents a low temperature case, and the surface is in phase separated. The blue curve represents a high temperature, and the surface is in rough phase.

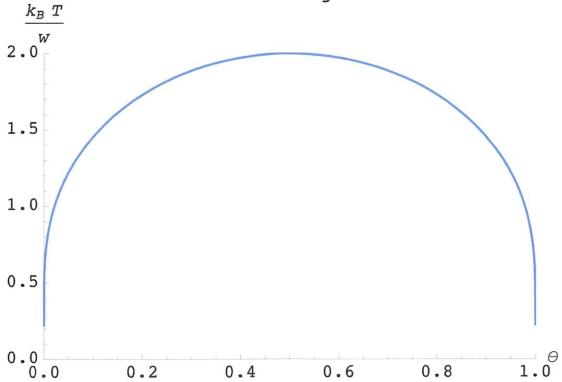


We can also plot the phase diagram. The phase diagram represents the minimum free energy situations. We can just take the first derivative of the above equation to find the extremum of free energy.

$$\frac{\partial}{\partial \theta} \left(\frac{f_{adat}}{\omega} \right) = 0$$

$$\frac{kT}{\omega} = \frac{-4(1-\theta) + 4\theta}{-\ln(1-\theta) + \ln\theta}$$

Phase Diagram



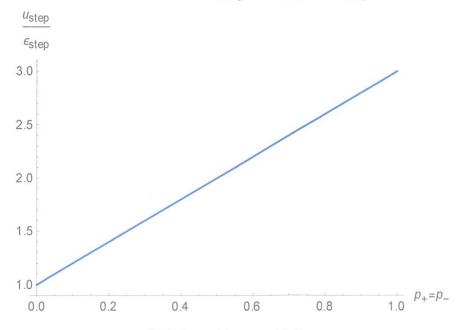
b)

From Eq. 6.13 in Taso's book, we can write down the free energy and entropy of step.

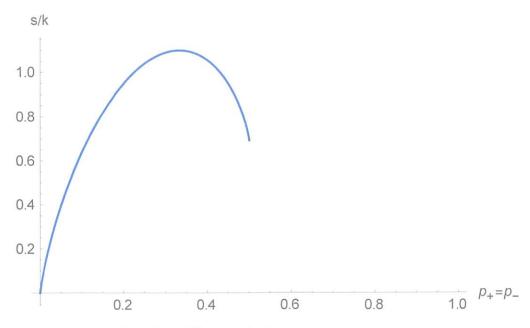
$$u_{step} = \epsilon_{step} + 2\epsilon_{kink}p_{-}$$

$$-\frac{s_{step}}{k} = 2p_{-}\ln(p_{-}) + (1 - 2p_{-})\ln(1 - 2p_{-})$$

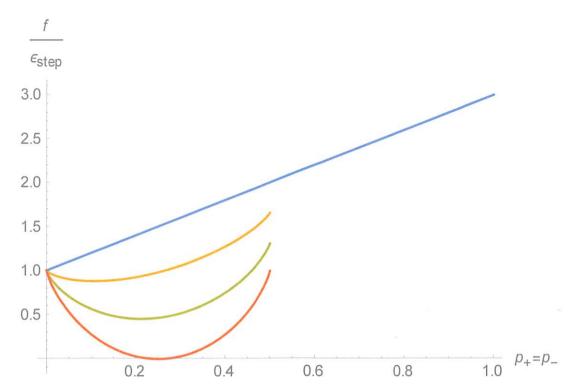
$$f_{step} = u_{step} - Ts_{step}$$



Step energy v.s probability of having kinks.

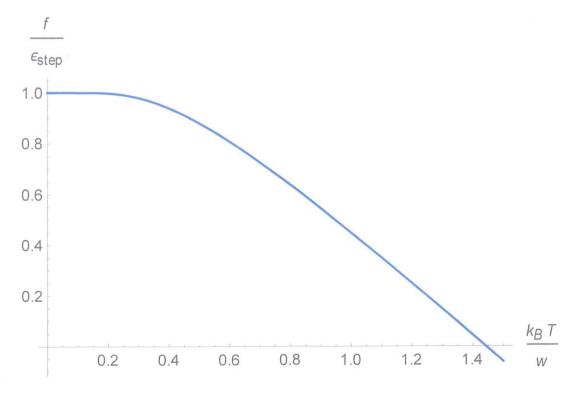


Entropy v.s probability of having kinks.



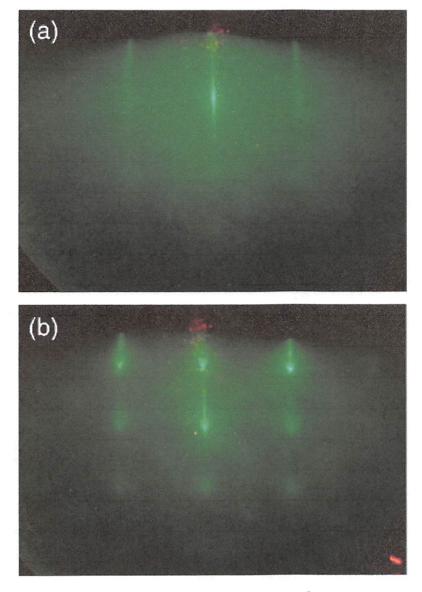
Free energy v.s probability of having kinks. Blue corresponds to zero temperature. Orange corresponds to $\frac{kT}{\omega}=0.5$. Green corresponds to $\frac{kT}{\omega}=1$.

Red corresponds to $\frac{kT}{\omega} = 1.45$.



c)

For the first surface roughing or phase separated case, it is very common in MBE system to use RHEED to observe these phenomenon. By the RHEED patterns, we can tell whether the growing surface is in layer by layer mode or island mode. We can change substrate temperature or source beam flux to drive the sample's surface states into different regimes in the phase diagram.



- (a) RHEED pattern of smooth GaN surface.
- (b) RHEED pattern of rough GaN surface.

If we want to do in-situ measurement on the surface behavior, RHEED probably is the best choice. For post-characterization, AFM or STM might be another choice to exactly determine the surface state through scanning image.

5.1) a. Given the potential energy $U(x) = c_2x^2 - c_3x^3 - c_4x^4$, the thermal awayse from bottzmumn statistics is $(x) = \int_{-\infty}^{\infty} dx \, x \, e^{-\beta u}$ for small anhamicity: $e^{-\beta u} = e^{-\beta c_2x^2} (1 + c_3x^3 + c_4x^4), \quad \delta 0: \quad \overline{Z}$ $c_{\infty} = e^{-\beta u} = e^{-\beta u} = e^{-\beta u} = e^{-\beta u} = e^{-\beta u}$ $e^{-\beta u} = e^{-\beta u} = e^{-\beta u} = e^{-\beta u} = e^{-\beta u}$ $e^{-\beta u} = e^{-\beta u} = e^{-\beta u} = e^{-\beta u} = e^{-\beta u}$ of $dx \times e^{-\beta t} = \int_{-\infty}^{\infty} dx e^{-\beta c_2 x^2} (x + c_3 x^4 + c_4 x^5) \times \text{and } x^5 \text{ ar odd, } e^{-\beta c_2 x^2} \text{ is erm, so}$ they integrate to 0, \Rightarrow 0 \Rightarrow $\int_{-\pi}^{\infty} dx e^{-\beta U} = \int_{-\pi}^{\infty} dx e^{-\beta C_2 X^2} \left(1 + C_2 X^2 + C_4 X^4 \right) = \frac{\sqrt{\pi}}{4 C_5^{5/2}} \left(\frac{3C_4}{\beta^{3/2}} + \frac{4C_5^2}{\beta^{3/2}} \right)$ So in total $(x) = \frac{3c_3}{C_2^{5/2}R^{3/2}}(C_2^{5/2})(\frac{R^{342}}{3C_4 + 4C_2^2R}) = \frac{3c_3kT}{4C_2^2 + 3C_4kT}$ usual. Newlecting Cy, $\frac{\partial (x)}{\partial T} = \frac{\partial}{\partial T} - \frac{3C_3K}{4C_2^2} = \frac{3C_3K}{4C_2^2}$ b. Starting with I next = I Naturaly, we need Na: Note Na = - (No. DT) and in the steady state (3Na =0) => We = Nn - YaVaTT at, where the vectors have been dropped. Right away we can see the first term will integrate to 0, because No wa = N-a w-a and Va = -V-a, so 5 Nawatra = - 5 Natural so the sum =0. Now w and a are continuous, so we need to convert the sum into an integral: Thent = [National guisding, whose the density of states how been used, and now the integration is wirit is instead of q. Na = tw/kt by box- Finastin state, so allow = (etw/kt) 2 etw/kt tw (-12) => Thent = (wmax - rava VT to etw/ct_1)2 to va g widow. I next = $-k_L\nabla T$, and also $g(g) = \frac{q^2}{2n^2V_s}$, assuming linear dispersion $V_2 = V_s = speed of sound$ and $\omega = qv$. So $g(\omega) = \frac{\omega^2}{2\pi^2 v_s^3}$. All together, then

Or
$$V_{L} = \frac{\hbar^{2}}{VT^{2}} \frac{1}{2\pi^{2}v_{s}} \int_{b}^{\omega_{max}} \frac{e^{\hbar\omega/kT}}{(e^{\hbar\omega/kT}-1)^{2}} d\omega$$
 Making the sub. $X = \frac{\hbar\omega}{kT} d\omega$:

$$= \sum_{k} K_{L} = \frac{\hbar^{2}}{kT^{2}} \frac{1}{2\pi^{2}v_{s}} \frac{kT}{\hbar} \left(\frac{kT}{\hbar}\right)^{H} \int_{b}^{x_{max}} \frac{e^{x}}{2\pi^{2}v_{s}} dx$$

$$= \sum_{k} \frac{kT}{2\pi^{2}v_{s}} \frac{kT}{\hbar} \left(\frac{kT}{\hbar}\right)^{H} \int_{b}^{x_{max}} \frac{e^{x}}{2\pi^{2}v_{s}} dx$$

$$= \sum_{k} \frac{kT}{2\pi^{2}v_{s}} \left(\frac{kT}{\hbar}\right)^{3} \int_{b}^{0} \frac{e^{\lambda v_{s}}}{2\pi^{2}(e^{x}-1)^{2}} dx$$

$$= \sum_{k} \frac{kT}{2\pi^{2}v_{s}} \left(\frac{kT}{\hbar}\right)^{3} \int_{b}^{0} \frac{e^{\lambda v_{s}}}{2\pi^{2}v_{s}} dx$$

· A is a constant" that depends weakly on or C. K_= A MOSS · M is the avayer muss of the unit cell containing in atoms · O is the "traditional" Debye temperature, determined from specific heat, that takes into accord all available males, not just concerns.

· & is the volume per whom

· 7 is the Grüneisen parameter, which channeleizes the anharmicity of the mutarial defined by $z = -\frac{d \ln \omega_c}{d \ln V}$

. T is the termocratur

in is the # of atoms in the unit cell

At 300 K, the value I gel are

GaAs: 0,55 Wen' K-1 GaN: 2.01 Wen' K-1 Si: 0.59 W cm' K' Sic: 5, 61 W cm' K- BN: 11,05 W cm' K-AIN: 3.82 Wcm K-1

Diamond: 16.42 W cm' K-

Using the parameters in the article, and $O_a = On^{-1/3} \Rightarrow K = A \frac{MO_n S n^{1/3}}{7^2T}$ Some of these are stabily different from what they report, best in theory we should be using the scare equation ...

d. Compound semiconductor allows and superluttices are made up of different types of atims, so phonon scuttering is greatly increased and the thermal conductivity decreases. Each different about effectively acts like an impunity with a different muss, and the muss contract causes the Ki contract.

In the same way, isotopes have a different mass than the normal atoms and also scatter phonons and therefore also decrese the thermal conductivity. Again the different isotopes act like imprities.

Generally electronic devices like transistors need a high Harmal conductivity because the heating due to transister density is currently are of the biggest fuctor presenting ICs from being fisher than ~3 GHz. Lasers and LEOs also require a high Ke to dissipate heat from non-radiative relaxations.

Low thermal conductivity is needed in muterials with a Strong Hermoelectric effect, If the electrical conductivity is high and the Homal conductivity is low, a temperature difference can induce a voltage different / current. If the thermal conductivity is too high, the temperature difference will just dissipate right away

5.2) 1, a. The question says you want "at least 3 man-free path lengths" from the surce to the substrate, but I'm assuming they mean you want the path from source to substrate to be 1/3 of the mean free path to avoid significant southerin:

where
$$\gamma$$
:
$$\lambda = 90 \text{ cm}$$

$$\sigma = 4 \times 10^{-15} \text{ cm}^{2}$$

$$T = 300 \text{ K}$$

$$A = 300 \text{ K}$$

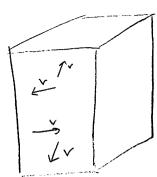
b. Now with T=1000K, P= 1200 = 2.7 x10-2 Pa

2, a. The flux is related to the pressure by $F = 2.63 \times 10^{17} \frac{P}{mT} cm^{7} s^{-1}, so P = F mT Pa is in cm^{7} s^{-1}, m is in amu, T in k$ $= P_{0u} = 0.502 Pa P_{Asy} = 29.45 Pa$

b. $\lambda = \frac{kT}{12\sigma^2}$, so using Too and Pass with $\sigma = 4 \times 10^{-15}$ em²

C. If the assumption that Asy is really prevelent from the scare to the substrute in the same path as the Ga is valid, then the Asy would Scutter the Ga significantly because the distance between source and substrate is >> 1 mm. On the other hand, in reality the beams may not overlap the whole way, and also the atoms are many mostly in the same direction, so in reality the scuttering would happen less frequently,

5.3) a. Given an ideal gas in a container.



The gas is main at an average speed v. Own the Maxwell-Boltzmann distribution:

The gas also has some pressure $P: PV=NKT=\sum_{V} \frac{N}{V}=n$ = cancentration = $\frac{P}{KT}$

Finally, the flux on I flat surface is $\frac{n\overline{v}}{2},\frac{1}{2}$, where I factor of $\frac{1}{2}$ comes from the fact that half the particles are travellio in the right direction (at the Surface) and half are travellign the wrong direction. The other 1/2 comes from the fact that some of the particles are not hilling the surface directly, so! the not result is a reductive of 1/4.

So:
$$F = \frac{nv}{4} = \frac{\rho}{kT} \frac{1}{4} \int \frac{8kT}{\pi m} = \frac{\rho}{2\pi m kT}$$

b. At P=10-10 torr, and m(N2)=28 amu = 4.65 × 10-26 kg

$$P = 10^{-1} \text{ for } and \text{ in cives = 20 cmm}$$

$$= 1.35 \times 10^{-8} \text{ Pa}$$

$$= 1.35 \times 10^{-8} \text{ Pa}$$

$$= \frac{P}{12 \text{ m/kT}} = \frac{3.82 \times 10^{14} \text{ m}^{-3} \text{ s}^{-1}}{3.82 \times 10^{14} \text{ m}^{-3} \text{ s}^{-1}}$$
For a typical atom density of $5 \times 10^{14} \text{ cm}^{-2}$

$$= \frac{P}{12 \text{ m/kT}} = \frac{3.82 \times 10^{14} \text{ m}^{-3} \text{ s}^{-1}}{3.82 \times 10^{14} \text{ m}^{-3} \text{ s}^{-1}}$$
For a typical atom density of $5 \times 10^{14} \text{ cm}^{-2}$

each gouth site (lattice point) gets hit with F = 76 ×10-5 atoms /sec = 0.28 atoms/hor. So on average each site is hit - once every 4 hours, but then

it has to stick and the sticking parameter is usually very low so to a very good approximation no growth will occur.

C. In this case, P== P(Uc) because there are basically no gas in the chamber before. At this pressure, and with m(U)=16 amu: 2,66×10-26 kg

$$F = \frac{P}{\sqrt{2\pi m^2 T}} = 5.05 \times 10^{15} \text{ m}^{-2} \text{ s}^{-1}. \text{ For } GaN, \ \ N = 8.9 \times 10^{22} \text{ cm}^{-3}$$

50 # of atoms per aren = n2/3 = 2 × 1019 cm2 = 2 × 1019 m-2 and the rate of replacement is \frac{F}{# perara} . S = 1.26 × 10⁻⁵ atoms / sec , or in 10 min => 0.00 758 atoms

material will have a small layer doped with Oxygen, with d. The reacting No'= (1.52 × 10'3 cm2) 3/2 = 5.93 × 10'9 cm3, so the band diagram will doping density look like:

where the width, and the difference in Ex hus been exadurated. No No No

Instrully the Fermi level was at EF-Ec = KTIN No , and in the O-doped region $E_p^* - E_z = kT \ln \frac{N_0!}{N_{CO}}$, assuming $N_0! = N_p!$, i.e. fill ionization, and also making the approximation that the total doping is No! from the oxygen, because No >> No

So U = E = E = E = KT In No - E - KT In No = KT In No = [165 mcV] is the bornier height for holes.

a. For a surface with surface coverage o, and atoms that make bonds with enorgy w, the energy of a single adatom is the ble it is missing 4 bonds. The probability that 4 of the neighbors are also adatoms is a cuch, though, So each adatom actually has an energy of Har-4w0=4w0=4wll-0). Finally, the probability of an adulm existing is 0, so the average energy per site is HWO(1-0) The mixing entropy comes from the mixing of adatom sites and vucencies,

In total, normalized by the bond energy, [f= 4wo(1-0) + KT[Oln0+(1-0)In(1-0)] So S = -k(0/n0+(1-0)/n(1-0)).

This is plotted above and below the phase diagram in Figure 6.2, for ICT/W= 2.5 and 1.5. In the middle is the phase disjourn obtained by minimizing flo at different KT/W values.

b. In general, for steps and kinks, the energy of formation is

Ustep = Exink (P. · P.) · Estep, where Estep is the energy scale of forming a step

and Exink is the energy scale of forming either a + kink or a - kink,

and P. and P. are the probabilities of forming a + kink or a - kink.

In this case we are looking at P. = P., i.e. the step is struight, so

Ustep = 28kink P. + Estep. We also assure 8kink = 8 step. so Ustep = 1+2P.

Estep

Aguin the same entopy of mixing is used, but this time with the 3 possibilities.

P. = + kink, P. = - Kink, Po = No Kink, So

 $S_{step} = -k \left(P_{+} \ln P_{+} + P_{-} \ln P_{-} + P_{-} \ln P_{0} \right), \text{ and } uith \text{ our assumptions}$ $P_{-} = P_{+} \text{ and } 2P_{-} + P_{0} = 1 \implies P_{0} = 1 - 2P_{0}$

5, RP = - 2KP_Inp_ - (1-2P_)In (1-2P-)

So in total, fstep = 1+2P-+ 12T [2P-InP-+ (1-2P-)] [
Estep

The normalized Ustro. Sstep, and fstep are shown in Figure Ce.Ce, on the left.

In particular, fstep is show at KT = 0, 0.5, 1.0, and 1.45. The equilibrium

Free encaies at a given KT are also shown on the right. These are calculated by minimizing fster, and plotting the minimum fstep/2step.

minimiting foton, and plotting the minimum foto/Estep, C. Both of these effects, considering adultons excitations and extended step excitations roult in a roughening of the sustance of a high enough temperature. In the asse of adutoms, this is seen from the phase transition between phase separated and smooth. In the cuse of steps, this is seen as flestep to after a critical temperator which implies that steps from sportunusly. From the culculations, the critical temperature Par steps is locar than that his adulture, so physically I would expect a real system to first develop isolated steps, and then become totally rough as temperature is increased. One may to probe this in the MBE chamber is to use RHEED while changing the surface temperature. This would be done while growth is stopped, as both these offects happen as a result of temperature changes and not because of growth. So I would first you a moderal, using RHEED first to tell when the converge is about 0.8 by tracking the oscillations of the intensity. At this point there should almost be a complete monolayer that is phase separated, so the intensity of the differentiar spots should be high. I would then increase the temperature without any purticle flux, and track the AHEED puttern

and intensity I would expect there to be 2 clear regions: at some To calculated from the step analysis the intensity would decrease slightly as steps begin to form spontaneously. Then out some higher To, adultant and vaccancies would become favorable and the BHEFO intensity would decrease can further. For this to be observed, the To for adultants must be below the melting point of the muterial.

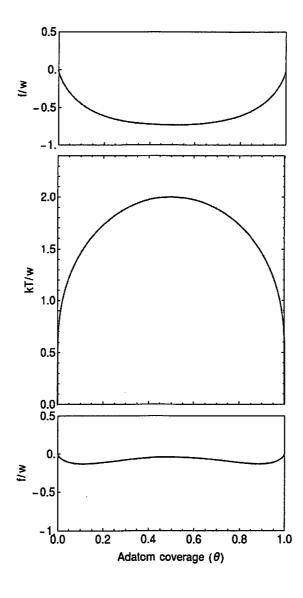


Figure 6.2: Phase diagram for surface roughening. Top and bottom show the normalized free energy at kT/w = 2.5 and kT/2 = 1.5, respectively. Middle shows the phase diagram, where below the line the surface is phase separated and above the line the surface is rough.

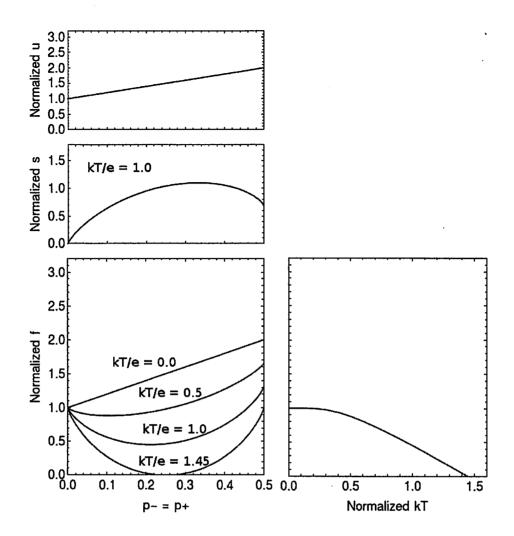


Figure 6.6: Normalized enthalpy (top), entropy (middle), and free energy (bottom) as a function of kink probability, for the case of a perfectly cut step, $\tan \varphi = 0$, and kink enthalpy equal to half of the step enthalpy. Also shown on the right is the free energy minimum as a function of kT/step enthalpy.